

## Recommended Reflow Soldering Conditions

This package is Surface Mount Device (SMD).

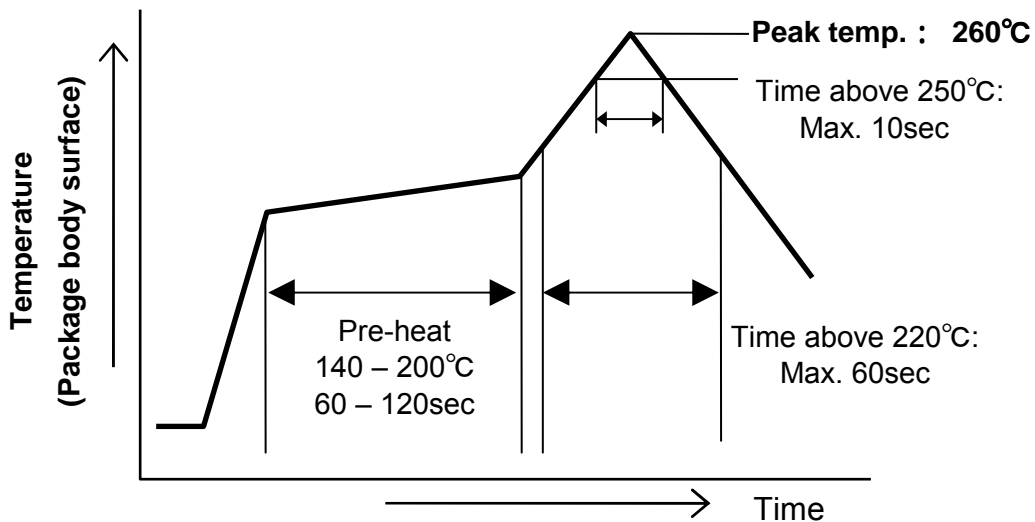
The resistance to soldering heat with SMD depends on storage conditions, soldering methods, and soldering conditions.

Please assemble packages according to the following conditions.

### Recommended Storage Conditions

	Conditions	Time
Before opening dry pack:	≤30°C85%RH	1 year
After opening dry pack:	≤30°C85%RH	1 year

### Recommended Reflow Profile



This package should be assembled with IR reflow, Full convection, or IR/Convection.

The allowable number of times with the reflow is Max. 2 times. This must be done in the above-mentioned condition (after opening dry pack).

\* Soldering iron conditions ( for packages with leads)

Temperature (Tip of the iron): ≤350°C, Time: ≤5sec, Max. 2 times / lead